Single 2-Input AND Gate

The NL17SZ08 is a single 2–input AND Gate in three tiny footprint packages. The device performs much as LCX multi–gate products in speed and drive. They should be used wherever the need for higher speed and drive are needed.

Features

- Tiny SOT-353, SOT-553 and SOT-953 Packages
- 2.7 ns T_{PD} at 5.0 V (typ)
- Source/Sink 24 mA at 3.0 V
- Overvoltage Tolerant Inputs
- Pin For Pin with NC7SZ08P5X, TC7SZ08FU and TC7SZ08AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

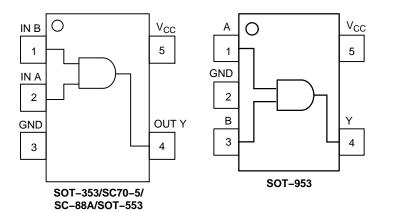




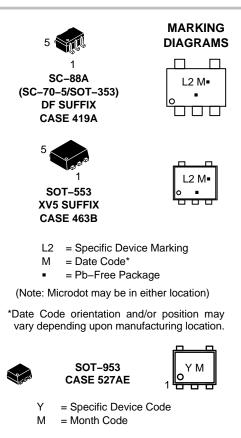


Figure 2. Logic Symbol



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ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

NL17SZ08

PIN ASSIGNMENT (SOT-353/SC70-5/SC-88A/SOT-553)

Pin	Function
1	IN B
2	IN A
3	GND
4	OUT Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	IN A
2	GND
3	IN B
4	OUT Y
5	V _{CC}
5	V _{CC}

FUNCTION TABLE

Ing	out	Output Y = AB
Α	В	Y
L	L	L
L	Н	L
Н	L	L
Н	н	н

MAXIMUM RATINGS

Symbol	Parameter		Value	Units
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage (SOT-353/SC70-5/SC-88A/SOT-553 Pack	ages)	-0.5 to +7.0	V
V _{OUT}	DC Output Voltage (SOT-953 Package)		–0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current		-50	mA
Ι _{ΟΚ}	DC Output Diode Current (SOT-953 Package)	±50	mA	
I _{OK}	DC Output Diode Current (SOT-353/SC70-5/SC-88A/SOT-553	3 Packages) V _{OUT} < GND	-50	mA
I _{OUT}	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
Τ _J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance	SOT-353 (Note 1) SOT-553	350 496	°C/W
PD	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD		man Body Model (Note 2) Machine Model (Note 3) ed Device Model (Note 4)	2000 200 N/A	V
ILATCHUP	Latchup Performance Above V_{CC} and Below GND at 125°C (No	te 5)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

4. Tested to JESD22–C101–A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Units
V _{CC}	DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage (SOT-353/SC70-5/SC-88A/SOT-553 Packa	ges)	0	5.5	V
V _{OUT}	DC Output Voltage (SOT-953 Package)		0	V _{CC}	V
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 3.0 V ±0.3 V V _{CC} = 5.0 V ±0.5 V	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

			V _{cc}	T,	_A = 25°	C	–55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High–Level Output Voltage V _{IN} = V _{IL} or V _{IH}	$I_{OH} = -100 \ \mu A$ $I_{OH} = -3 \ m A$ $I_{OH} = -8 \ m A$ $I_{OH} = -12 \ m A$ $I_{OH} = -16 \ m A$ $I_{OH} = -24 \ m A$ $I_{OH} = -32 \ m A$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.52 2.1 2.4 2.7 2.5 4.0		$\begin{array}{c} V_{CC} - 0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{array}$		V
V _{OL}	Low–Level Output Voltage V _{IN} = V _{IH} or V _{OH}	$I_{OL} = 100 \ \mu A$ $I_{OL} = 3 \ mA$ $I_{OL} = 8 \ mA$ $I_{OL} = 12 \ mA$ $I_{OL} = 16 \ mA$ $I_{OL} = 24 \ mA$ $I_{OL} = 32 \ mA$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μΑ
I _{OFF}	Power Off Leakage Current (SOT-353/SC70-5/ SC-88A/SOT-553 Packages)	$V_{IN} = 5.5 V \text{ or}$ $V_{OUT} = 5.5 V$	0			1		10	μΑ

DC ELECTRICAL CHARACTERISTICS

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

			V _{CC}		Γ _A = 25°C	;	–55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PLH}	Propagation Delay	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.65	2.0	6.3	12	2.0	12.7	ns
t _{PHL}	(Figure 3 and 4)	$R_L = 1 M\Omega, C_L = 15 pF$	1.8	2.0	6.2	10	2.0	10.5	
		$R_L = 1 M\Omega, C_L = 15 pF$	2.5 ± 0.2	0.8	3.4	7.0	0.8	7.5	
		$R_L = 1 M\Omega$, $C_L = 15 pF$	3.3 ± 0.3	0.5	2.6	4.7	0.5	5.0	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$		1.5	3.3	5.2	1.5	5.5	
		$R_L = 1 M\Omega, C_L = 15 pF$	5.0 ± 0.5	0.5	2.2	4.1	0.5	4.4	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$		0.8	2.7	4.5	0.8	4.8	

AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	>4.0	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	25	pF
	(Note 6)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	30	

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

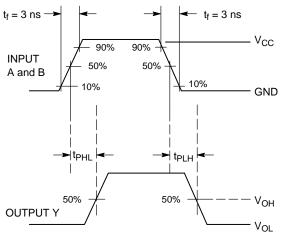
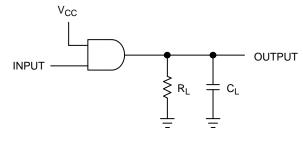


Figure 3. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

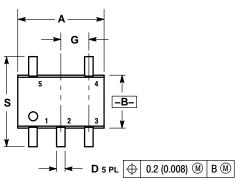
Device Order Number	Package Type	Tape and Reel Size [†]
NL17SZ08DFT2G	SC-88A/SC-70-5/SOT-353 (Pb-Free)	3000 / Tape & Reel
NL17SZ08XV5T2G	SOT–553 (Pb–Free)	4000 / Tape & Reel
NL17SZ08P5T5G	SOT–953 (Pb–Free)	8000 / Tape & Reel

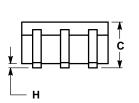
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

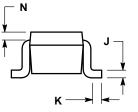
NL17SZ08

PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE L



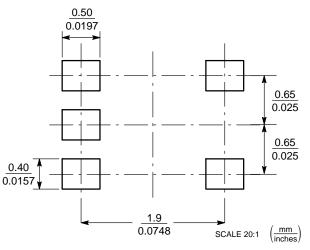




NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
н		0.004		0.10
J	0.004	0.010	0.10	0.25
Κ	0.004	0.012	0.10	0.30
Ν	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

SOLDER FOOTPRINT*



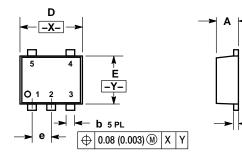
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553, 5 LEAD **XV5 SUFFIX** CASE 463B ISSUE C

Η_E

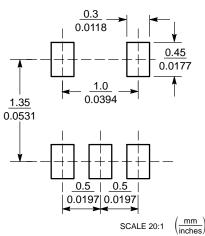
С



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. INCHES

	MILLIMETERS		LIMETERS INCI		INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
Е	1.15	1.20	1.25	0.045	0.047	0.049
е		0.50 BSC			0.020 BSC)
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.55	1.60	1.65	0.061	0.063	0.065

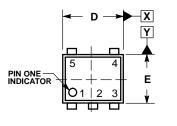
RECOMMENDED **SOLDERING FOOTPRINT***



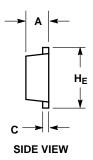
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

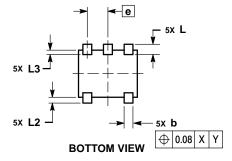
PACKAGE DIMENSIONS

SOT-953 CASE 527AE **ISSUE E**



TOP VIEW





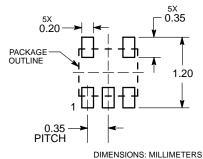
NOTES 1. DIMENSIONING AND TOLERANCING PER ASME

Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE 3.

- MINIMUM THICKNESS OF THE BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. 4

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.34	0.37	0.40		
b	0.10	0.15	0.20		
С	0.07	0.12 0.17			
D	0.95	1.00	1.05		
Е	0.75	0.80	0.85		
е		0.35 BS	С		
HE	0.95	1.00	1.05		
L	0.175 REF				
L2	0.05	0.10	0.15		
L3			0.15		

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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